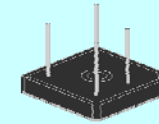


MATERIAL COMPOSITION DECLARATION

Supplier: Fagor Electrónica S. Coop

Package: FB -L



Part Number:

Description: Power Bridge Rectifier (lead wire)

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS(mg)	MATERIAL MASS(%)	ELEMENT NAME COMPOSITION	CAS N°	ELEMENT % (BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD FRAME	Electrolitic Copper	3.255,600	24,89%	Cu Ag	7440-50-8 7440-22-4	99,9 0,1	< 2	< 2	< 2	< 2	< 5	< 5
ENCAPSULATION	Capsule	5.987,350	45,77%	Al	7429-90-5	58,70	< 2	< 2	< 2	< 2	< 5	< 5
				Fe	7439-89-6	0,24						
				SiO2 (Fused Silica)	60676-86-0	28,7-30,75						
				Polyglycidyl Ether O-Cresol Formaldehyde								
				Novolac	29690-82-2	4,1-6,15						
				Phenolic Resin	9003-35-4	2,05-4,1						
				Sb2O3	1309-64-4	0,41-3,42						
	Brominated Epoxy resin	40039-93-8	0,41-3,42									
	Epoxy Resin & Hardener	3.755,000	28,71%	bis-(epoxiciclohexil)-metilcarboxilato	2386-87-0	20,0-28,0	< 2	< 2	< 2	< 2	< 5	< 5
				Epoxy resin of bisfenol-A- epiclorhidrina	25068-38-6	10,0-18,0						
SiO2 (Fused Silica)				60676-86-0	15,0-43,0							
anhidrido metil-tetrahidroftálico				26590-20-5	27,0-39,0							
CHIP	Doped Silicon Glass Passivated	25,250	0,19%	Si Ni SiO2 PbO2 Al2O3	7440-21-3 7440-02-0 7631-86-9 1309-60-0 1344-28-1	90,6-92,1 0,9-1,3 3,6-3,8 3,4-3,5 0,3-0,5	< 2	22445 (**)	< 2	< 2	< 5	< 5
SOLDER PASTE	Pb/Sn5 Solder Paste	43,650	0,33%	Pb Sn Sb	7439-92-1 7440-31-5 7440-36-0	92,8 - 95,0 4,5 - 5,5 0,2	< 2	940000 (*)	< 2	< 2	< 5	< 5
COATING	Silver 100%	13,150	0,10%	Ag	7440-22-4	99,9	< 2	< 2	< 2	< 2	< 5	< 5
WHOLE ITEM		13.080,00	100,00%									

Exception according to annex of Directive 2002/95/EC (RoHS):

* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

** Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes